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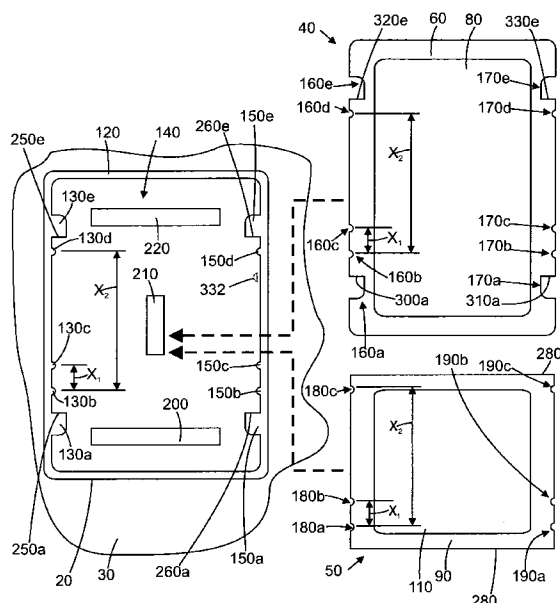


FIG. 3

(57) Abstract: Various sockets (20, 320) for multiple sizes of chip package substrates (40, 335) (50, 337) are disclosed. In one aspect, an apparatus is provided that includes a socket (20, 320) that has a peripheral wall (120, 340) defining an interior space (140, 350) adapted to receive either of a first semiconductor chip package substrate (40, 335) and a second semiconductor chip package substrate (50, 337). The first semiconductor chip package substrate (40, 335) has a first size and a first plurality of structural features (160a, 420a) and the second semiconductor chip package substrate (50, 337) has a second size different than the first size and a second plurality of structural features (180a, 490a). The socket (20, 320) has a third plurality of structural features (130a, 130b, 390a) operable to engage the structural features of either of semiconductor chip package substrates to selectively enable the first semiconductor chip package substrate (40, 335) to be located at a first preselected position in the interior space (140, 350) and the second semiconductor chip package substrate (50, 337) to be located at a second preselected position in the interior space (140, 350).



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